

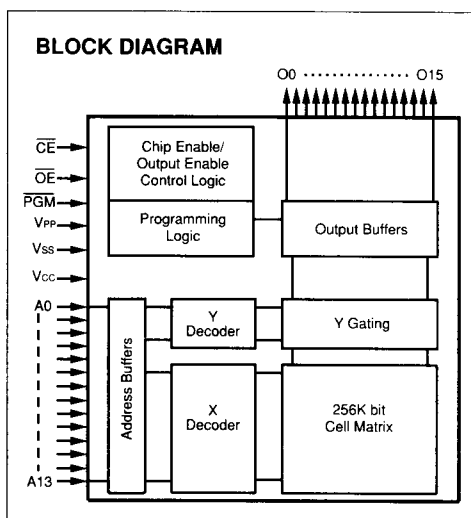
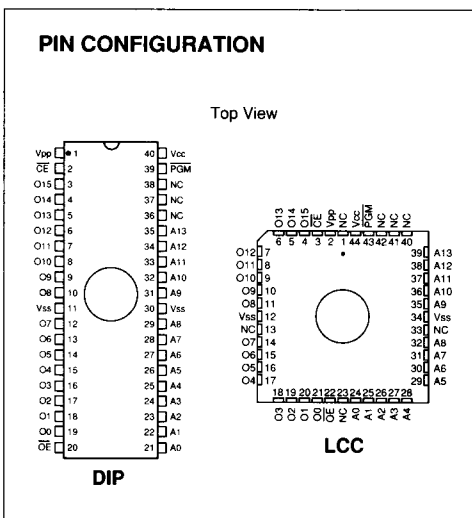
256K (16K x 16) High Speed CMOS Erasable PROM

FEATURES

- 16 bit configuration
- High speed performance
—55ns access time available
- CMOS Technology for low power consumption
—90mA Active current
—50mA Standby current
- WordWide architecture offers space saving over Bytewide memories
- Organized 16K x 16: JEDEC standard pinouts
—40-Pin ceramic dual in line package
—44-Pin ceramic leadless chip carrier
- Temperature range available:
—Commercial: 0°C to +70°C
—Industrial: -40°C to +85°C

DESCRIPTION

The Microchip Technology Inc. 27HC1616 is a CMOS 16K x 16 (256K) Programmable Read Only Memory. The device operates at Bipolar PROM speeds but uses far less current than any Bipolar PROM. The 27HC1616 is an excellent choice for any application requiring blazing speeds and low power consumption. The word wide (16 bit) architecture can replace two 8 bit EPROMs in any 16 bit application saving valuable printed circuit space and components costs. Typical applications for the 27HC1616 include automotive systems control, high speed modems, digital signal processing, or any application that uses the 80386, 68030, 29000, etc. high performance microprocessors.



PIN FUNCTION TABLE	
Name	Function
A0 - A13	Address Inputs
\overline{CE}	Chip Enable
\overline{OE}	Output Enable
PGM	Program Enable
VPP	Programming Voltage
O0 - O15	Data Output
VCC	+5V Power Supply
VSS	Ground
NC	No Connection; No Internal Connection

ELECTRICAL CHARACTERISTICS

Maximum Ratings*

VCC and input voltages w.r.t. VSS -0.6V to +7.25V
 VPP voltage w.r.t. VSS during programming -0.6V to +14.0V
 Voltage on A9 w.r.t. VSS -0.6V to +13.5V
 Output voltage w.r.t. VSS -0.6V to VCC +1.0V
 Temperature under bias -65°C to 125°C
 Storage temperature -65°C to 150°C
 ESD protection on all pins 2KV

*Notice: Stresses above those listed under "Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

READ OPERATION DC Characteristics		VCC = +5V ±10% Commercial: Tamb= 0°C to 70°C Industrial: Tamb= -40°C to 85°C					
Parameter	Part	Status	Symbol	Min	Max	Units	Conditions
Input Voltages	all	Logic "1" Logic "0"	V _{IH} V _{IL}	2.0 -0.1	VCC+1 0.8	V V	
Input Leakage	all		I _{LI}	-10	10	µA	V _{IN} = -0.1 to VCC + 1.0V
Output Voltages	all	Logic "1" Logic "0"	V _{OH} V _{OL}	2.4	0.45	V V	I _{OH} = -2mA I _{OL} = 8mA
Output Leakage	all		I _{LO}	-10	10	µA	V _{OUT} = -0.1 to VCC + 0.1V
Input Capacitance	all		C _{IN}		6	pF	V _{IN} = 0V; Tamb = 25°C; f = 1MHz
Output Capacitance	all		C _{OUT}		12	pF	V _{OUT} = 0V; Tamb = 25°C; f = 1MHz
Power Supply Current, Active	all	TTL input	I _{CC}		90	mA	VCC = 5.5V; VPP = VCC f = 2MHz; $\overline{OE} = \overline{CE} = V_{IL}$; I _{out} = 0mA; V _{IL} = -0.1 to 0.8 V; V _{IH} = 2.0 to VCC; Note 1
Power Supply Current, Standby	all		I _{CC}		50	mA	
I _{PP} Read Current	all	Read Mode	I _{PP}		100	µA	VPP = 5.5V
VPP Read Voltage	all	Read Mode	VPP	VCC-0.7	VCC	V	Note 2

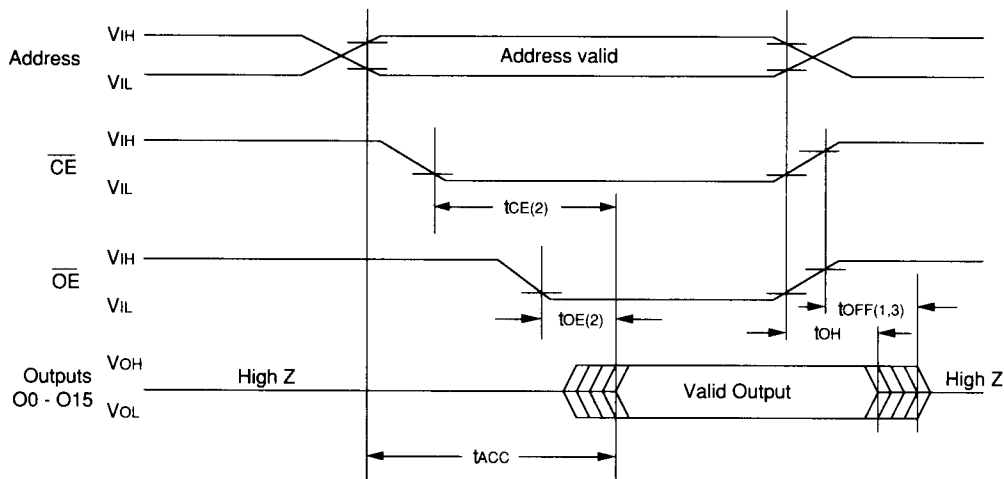
Notes: (1) Active current increases 2 mA per MHz up to operating frequency.
 (2) VCC must be applied simultaneously or before VPP and be removed simultaneously or after VPP.

READ OPERATION AC Characteristics

AC Testing Waveform: $V_{IH} = 3.0\text{ V}$ and $V_{IL} = 0.0\text{ V}$; $V_{OH} = V_{OL} = 1.5\text{ V}$
 Output Load: 1 TTL Load + 30 pF
 Input Rise and Fall Times: 5 nsec
 Ambient Temperature: Commercial: $T_{amb} = 0^\circ\text{ C}$ to 70° C
 Industrial: $T_{amb} = -40^\circ\text{ C}$ to 85° C

Parameter	Part	Sym	27HC1616-55		27HC1616-70		Units	Conditions
			Min	Max	Min	Max		
Address to Output Delay	all	tACC		55		70	ns	$\overline{CE} = \overline{OE} = V_{IL}$
\overline{CE} to Output Delay	all	tCE2		35		45	ns	$\overline{OE} = V_{IL}$
\overline{OE} to Output Delay	all	tOE		30		35	ns	$\overline{CE} = V_{IL}$
\overline{CE} or \overline{OE} to O/P High Impedance	all	tOFF	0	20	0	25	ns	
Output Hold from Address \overline{CE} or \overline{OE} , whichever occurs first	all	tOH	0		0		ns	

READ WAVEFORMS



- Notes: (1) t_{OFF} is specified for \overline{OE} or \overline{CE} , whichever occurs first
 (2) \overline{OE} may be delayed up to $t_{CE} - t_{OE}$ after the falling edge of \overline{CE} without impact on t_{CE}
 (3) This parameter is sampled and is not 100% tested.

27HC1616

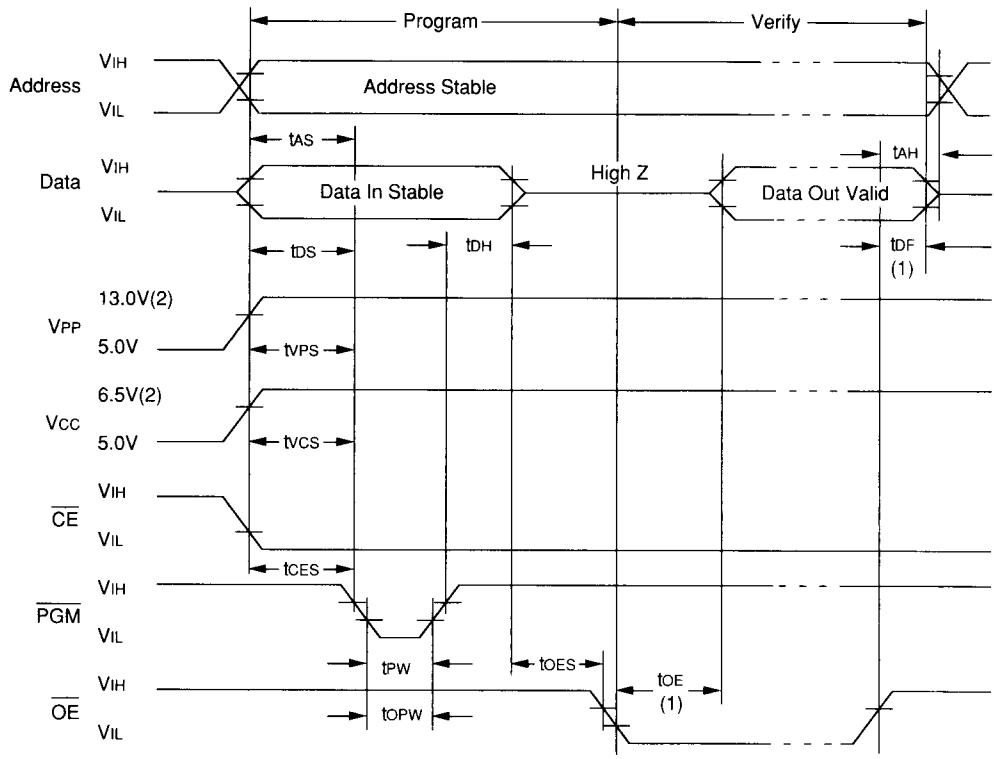
PROGRAMMING DC Characteristics		Ambient Temperature: 25° C ±5° C For V _{PP} and V _{CC} Voltages refer to Programming Algorithm				
Parameter	Status	Symbol	Min	Max	Units	Conditions
Input Voltages	Logic "1"	V _{IH}	2.0	V _{CC} +1	V	
	Logic "0"	V _{IL}	-0.1	0.8	V	
Input Leakage		I _{LI}	-10	10	µA	V _{IN} = -.1V to V _{CC} + 1.0V
Output Voltages	Logic "1"	V _{OH}	2.4		V	I _{OH} = - 2mA I _{OL} = 8mA
	Logic "0"	V _{OL}		0.45	V	
V _{CC} Current, program & verify		I _{CC}		90	mA	Note 1
V _{PP} Current,program		I _{PP}		50	mA	Note 1
A9 Product Identification		V _H	11.5	12.5	V	

Note: (1) V_{CC} must be applied simultaneously or before V_{PP} and removed simultaneously or after V_{PP}

PROGRAMMING AC Characteristics		AC Testing Waveform: V _{IH} = 2.4V; V _{IL} = 0.45V; V _{OH} = 2.0V and V _{OL} = 0.8V Ambient Temperature: 25° C ±5° C For V _{PP} and V _{CC} Voltages, refer to Programming Algorithm				
Parameter	Symbol	Min	Max	Units	Remarks	
Address Set-Up Time	t _{AS}	2		µs		
Data Set-Up Time	t _{DS}	2		µs		
Data Hold Time	t _{DH}	2		µs		
Address Hold Time	t _{AH}	0		µs		
Float Delay (2)	t _{DF}	0	130	ns		
V _{CC} Set-Up Time	t _{VCS}	2		µs		
Program Pulse Width (1)	t _{PW}	95	105	µs	100 µs typical	
$\overline{\text{CE}}$ Set-Up Time	t _{CES}	2		µs		
$\overline{\text{OE}}$ Set-Up Time	t _{OES}	2		µs		
V _{PP} Set-Up Time	t _{VPS}	2		µs		
Data Valid from $\overline{\text{OE}}$	t _{OE}		100	ns		

Notes: (1) For express algorithm, initial programming width tolerance is 100 µsec ±5%.
(2) This parameter is only sampled and not 100% tested. Output float is defined as the point where data is no longer driven (see timing diagram).

PROGRAMMING Waveforms



- Notes: (1) tDF and tOE are characteristics of the device but must be accommodated by the programmer
 (2) Vcc = 6.5V ±0.25V, VPP = VH = 13.0V ±0.25V for express algorithm

FUNCTIONAL DESCRIPTION

The 27HC1616 has the following functional modes:

—Operation: The 27HC1616 can be activated for data read, be put in standby mode to lower its power consumption, or have the outputs disabled.

—Programming: To receive its permanent data, the 27HC1616 must be programmed. Both a program and program/verify procedure is available. The Express programming algorithm is recommended.

The programming equipment can automatically recognize the device type and manufacturer using the identity mode.

For the general characteristics in these operation and programming modes, refer to the table.

Operation Mode	\overline{CE}	\overline{OE}	\overline{PGM}	VPP	A9	O0 - O15
Read	VIL	VIL	VH	VCC	X	Dout
Program	VIL	VH	VIL	VH	X	Din
Program Verify	VH	VIL	VH	VH	X	Dout
Program Inhibit	VH	X	X	VH	X	High Z
Standby	VH	X	X	VCC	X	High Z
Output Disable	X	VH	VH	VCC	X	High Z
Identity	VIL	VIL	VH	VCC	VH	Identity Code

X = Don't Care
 VH = 12.0 ±0.5V

OPERATION

Read Mode

For timing and AC characteristics refer to the tables Read Waveforms and Read Operation AC Characteristics.

The 27HC1616's memory data is accessed when

- the chip is enabled by setting the \overline{CE} pin low.
- the data is gated to the output pins by setting the \overline{OE} pin low.

Standby Mode

The standby mode is entered when the \overline{CE} pin is high, and the program mode is not defined. When these conditions are met, the supply current will drop from 90mA to 50mA.

Output Disable

This feature eliminates bus contention in multiple bus microprocessor systems. The outputs go to a high impedance when the \overline{OE} pin is high, and the program mode is not defined.

Programming/Verification

The 27HC1616 has to be programmed, and afterward the programmed information verified. Before these operations, the Identity Code can be read to properly set up automated equipment. Multiple devices in parallel can be programmed using the programming and inhibit modes.

Programming Algorithm

The "Express" algorithm has been developed to improve programming through-put times in a production environment. Up to 10 pulses of 100µsec each are applied until the byte is verified. No overprogramming is required. A flowchart of this algorithm is shown in Figure 2.

The programming mode is entered when:

- a) VCC is brought to the proper level
- b) VPP is brought to the proper VH level
- c) the \overline{OE} pin is high
- d) the \overline{CE} pin is low, and
- e) the PGM pin is pulsed low.

Since the erased state is "1" in the array, programming of "0" is required. The address of the memory location to be programmed is set via pins A0 - A13, and the data is presented to pins O0 - O15. When data and address are stable, a low going pulse on the \overline{CE} line programs that memory location.

Verify

After the array has been programmed, it must be verified to make sure that all the bits have been correctly programmed. This mode is entered when all of the following conditions are met:

- a) VCC is at the proper level
- b) VPP is at the proper VH level
- c) the \overline{OE} line is low
- d) the \overline{CE} pin is low, and
- e) the PGM line is high.

Inhibit Mode

When Programming multiple devices in parallel with different data only PGM needs to be under separate control to each device. By pulsing the PGM line low on a particular device, that device will be programmed, and all other devices with corresponding PGM or \overline{CE} held high will not be programmed with the data although address and data are available on their input pins.

Identity Mode

In this mode specific data is read from the device that identifies the manufacturer as Microchip Technology, and the device type. This mode is entered when pin A9 is taken to VH (11.5V to 12.5V). The \overline{CE} and \overline{OE} pins must be at VIL. A0 is used to access any of the two non-erasable bytes whose data appears on O0 - O7.

Pin →	Input	Output*								
Identity ↓	A0	O7	O6	O5	O4	O3	O2	O1	O0	Hex
Manufacturer	VIL	0	0	1	0	1	0	0	1	29
Device Type*	VIH	1	0	0	1	0	1	1	1	97

*Code subject to change.

Note: O15 - O8 are 00 for the manufacturer and device type code.

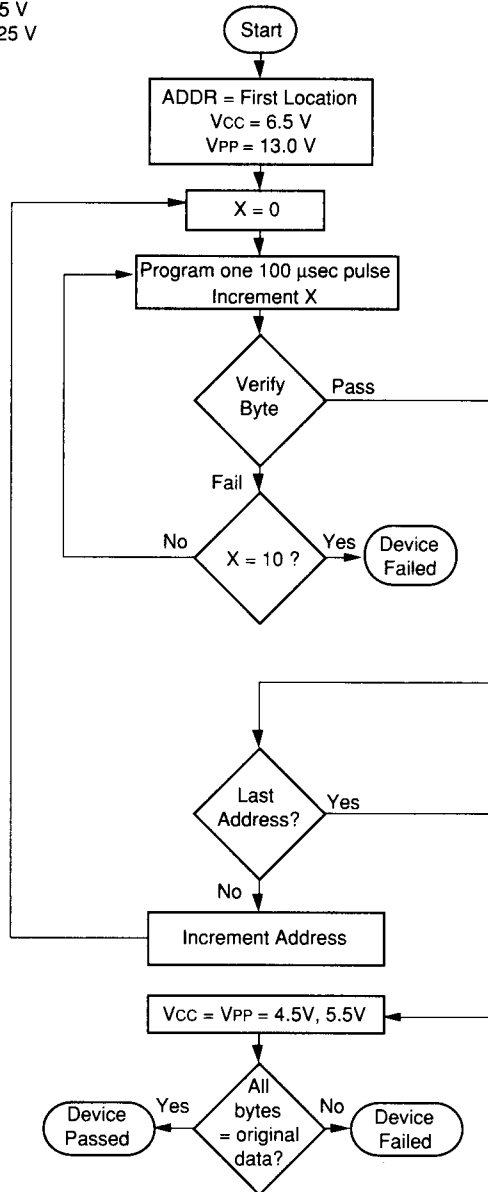
Erasure

Windowed products offer the ability to erase the memory array. The memory matrix is erased to the all "1"s state as a result of being exposed to ultra-violet light at wavelengths ≤ 4000 Angstroms (Å). The recommended procedure is to expose the erasure window of device to a commercial UV source emitting at 2537Å with an intensity of 12,000µW/cm² at 1". The erasure time at that distance is about 15 to 20 min.

Note: Fluorescent lights and sunlight emit rays at the specified wavelengths. The erasure time is about 3 years or 1 week resp. in these cases. To prevent loss of data, an opaque label should be placed over the erasure window.

**PROGRAMMING - FIGURE 1
EXPRESS ALGORITHM**

Conditions:
 $T_{amb} = 25^{\circ}C \pm 5^{\circ}C$
 $V_{CC} = 6.5 \pm 0.25V$
 $V_{PP} = 13.0 \pm 0.25V$



27HC1616

SALES AND SUPPORT

To order or to obtain information, e.g., on pricing or delivery, please use the listed part numbers, and refer to the factory or the listed sales offices.

PART NUMBERS

27HC1616 - 55 I / P

Package: J Cerdip DIP
K Ceramic Leadless Chip Carrier

Temperature Range: - 0° C to 70° C

Access Time: 55 55 nsec
70 70 nsec

Device: 27HC1616 256K (16K x 16) High Speed CMOS EPROM